

CGD982LC

1 GHz, 23 dB gain GaAs low current power doubler

Rev. 1 — 10 March 2014

Product data sheet

1. Product profile

1.1 General description

Hybrid amplifier module in a SOT115AE package, operating at a supply voltage of 24 V Direct Current (DC), employing Heterojunction Field Effect Transistor (HFET) GaAs dies.

1.2 Features and benefits

- Low power consumption
- Excellent linearity
- Optimized for PAL D loading
- Extremely low noise
- Excellent return loss properties
- Compliant to Directive 2002/95/EC, regarding Restriction of Hazardous Substances (RoHS)
- Gain compensation over temperature
- Rugged construction
- Unconditionally stable
- Thermally optimized design
- Adjustable supply current

1.3 Applications

- CATV systems operating in the 40 MHz to 1 GHz frequency range using PAL D channel conditions.

1.4 Quick reference data

Table 1. Quick reference data

Bandwidth 40 MHz to 1003 MHz; $V_B = 24$ V (DC); $Z_S = Z_L = 75 \Omega$; $T_{mb} = 35$ °C; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
G_p	power gain	$f = 50$ MHz	20.5	21.5	22.5	dB
		$f = 1003$ MHz	22	23	24	dB
CTB	composite triple beat	$V_o = 48$ dBmV at 862 MHz [1][2]	-	-65	-59	dBc
CSO	composite second-order distortion	$V_o = 48$ dBmV at 862 MHz [1][2]	-	-70	-60	dBc
I_{tot}	total current	pin 4 not connected [3]	345	365	385	mA
		pin 4 connected to ground [3]	-	315	-	mA

[1] 98 PAL D channels with 8 MHz bandwidth per channel; $[f = 47$ MHz to 862 MHz]; flat V_o till 862 MHz.

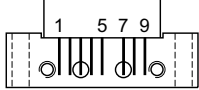
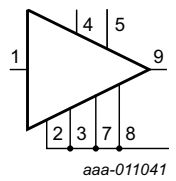
[2] Pin 4 not connected.

[3] Direct Current (DC).



2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	input		
2, 3	common		
4	I _{CC} adjust [1]		
5	+V _B		
7, 8	common		
9	output		

[1] The total supply current can be adjusted by pin 4. Grounding of pin 4 gives the lowest supply current while floating of pin 4 gives the maximum supply current.

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
CGD982LC	-	rectangular single-ended package; aluminium flange; 2 vertical mounting holes; 2 × 6-32 UNC and 2 extra horizontal mounting holes; 8 gold-plated in-line leads	SOT115AE

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _B	supply voltage		-	30	V
V _{i(RF)}	RF input voltage	single tone	-	75	dBmV
I _I	input current	on I _{CC} adjust (pin 4)	-10	0	mA
T _{stg}	storage temperature		-40	+100	°C
T _{mb}	mounting base temperature		-20	+100	°C

5. Characteristics

Table 5. Characteristics

Bandwidth 40 MHz to 1003 MHz; $V_B = 24$ V (DC); $Z_S = Z_L = 75\ \Omega$; $T_{mb} = 35\ ^\circ\text{C}$; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
G _p	power gain	f = 50 MHz	20.5	21.5	22.5	dB
		f = 1003 MHz	22	23	24	dB
SL _{sl}	slope straight line	f = 40 MHz to 1003 MHz [1]	0.5	-	2	dB
FL	flatness of frequency response	f = 40 MHz to 1003 MHz [2]	-	-	0.8	dB
RL _{in}	input return loss	f = 40 MHz to 160 MHz	20	-	-	dB
		f = 160 MHz to 320 MHz	20	-	-	dB
		f = 320 MHz to 640 MHz	19	-	-	dB
		f = 640 MHz to 870 MHz	17	-	-	dB
		f = 870 MHz to 1003 MHz	15	-	-	dB
RL _{out}	output return loss	f = 40 MHz to 160 MHz	20	-	-	dB
		f = 160 MHz to 320 MHz	20	-	-	dB
		f = 320 MHz to 640 MHz	19	-	-	dB
		f = 640 MHz to 870 MHz	17	-	-	dB
		f = 870 MHz to 1003 MHz	16	-	-	dB
NF	noise figure	f = 50 MHz	-	5.2	6.0	dB
		f = 1003 MHz	-	5.7	6.5	dB
Pin 4 not connected						
I _{tot}	total current	[3]	345	365	385	mA
98 PAL D channels						
CTB	composite triple beat	V _o = 48 dBmV at 862 MHz [4]	-	-65	-59	dBc
CSO	composite second-order distortion	V _o = 48 dBmV at 862 MHz [4]	-	-70	-60	dBc
Xmod	cross modulation	V _o = 48 dBmV at 862 MHz [4][5]	-	-60	-	dB
59 PAL D channels + 75 digital channels						
CTB	composite triple beat	V _o = 58.5 dBmV at 1003 MHz [6]	-	-72	-	dBc
CSO	composite second-order distortion	V _o = 58.5 dBmV at 1003 MHz [6]	-	-75	-	dBc
Xmod	cross modulation	V _o = 58.5 dBmV at 1003 MHz [5][6]	-	-67	-	dB
CCN	carrier-to-composite noise	V _o = 58.5 dBmV at 1003 MHz [6]	-	62	-	dBc

Table 5. Characteristics ...continued

Bandwidth 40 MHz to 1003 MHz; $V_B = 24\text{ V (DC)}$; $Z_S = Z_L = 75\ \Omega$; $T_{mb} = 35\text{ }^\circ\text{C}$; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Pin 4 connected to ground						
I_{tot}	total current		[3]	-	315	- mA
98 PAL D channels						
CTB	composite triple beat	$V_o = 48\text{ dBmV at }862\text{ MHz}$	[4]	-	-58	- dBc
CSO	composite second-order distortion	$V_o = 48\text{ dBmV at }862\text{ MHz}$	[4]	-	-69	- dBc
59 PAL D channels + 75 digital channels						
CTB	composite triple beat	$V_o = 58.5\text{ dBmV at }1003\text{ MHz}$	[6]	-	-61	- dBc
CSO	composite second-order distortion	$V_o = 58.5\text{ dBmV at }1003\text{ MHz}$	[6]	-	-74	- dBc
CCN	carrier-to-composite noise	$V_o = 58.5\text{ dBmV at }1003\text{ MHz}$	[6]	-	55	- dBc

[1] G_p at 1003 MHz minus G_p at 40 MHz.

[2] Flatness is defined as peak deviation to straight line.

[3] Direct Current (DC).

[4] 98 PAL D channels with 8 MHz bandwidth per channel; $[f = 47\text{ MHz to }862\text{ MHz}]$; flat V_o till 862 MHz.

[5] Measured at 55.25 MHz.

[6] 59 PAL D channels $[f = 49.75\text{ MHz to }543.25\text{ MHz}]$ + 75 digital channels $[f = 555.25\text{ MHz to }1003\text{ MHz}]$ (-10 dB offset); 13.5 dB tilt extrapolated to 1003 MHz.

6. Package outline

Rectangular single-ended package; aluminium flange; 2 vertical mounting holes;
2 x 6-32 UNC and 2 extra horizontal mounting holes; 8 gold-plated in-line leads

SOT115AE

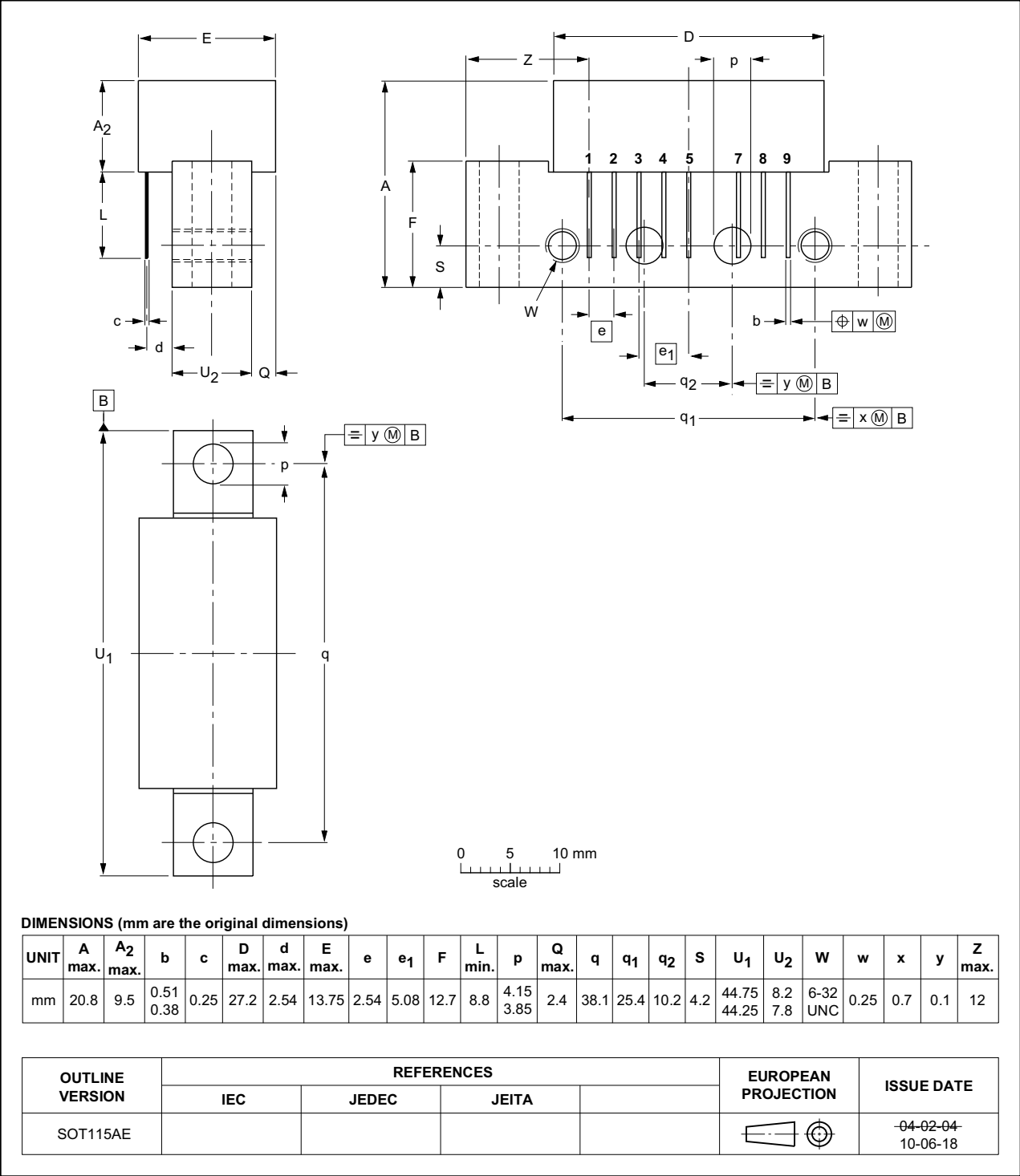


Fig 1. Package outline SOT115AE

7. Abbreviations

Table 6. Abbreviations

Acronym	Description
CATV	Community Antenna TeleVision
ESD	ElectroStatic Discharge
GaAs	Gallium-Arsenide
PAL D	Phase Alternate Line standard D
UNC	UNified Coarse

8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
CGD982LC v.1	20140310	Product data sheet	-	-

9. Legal information

9.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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